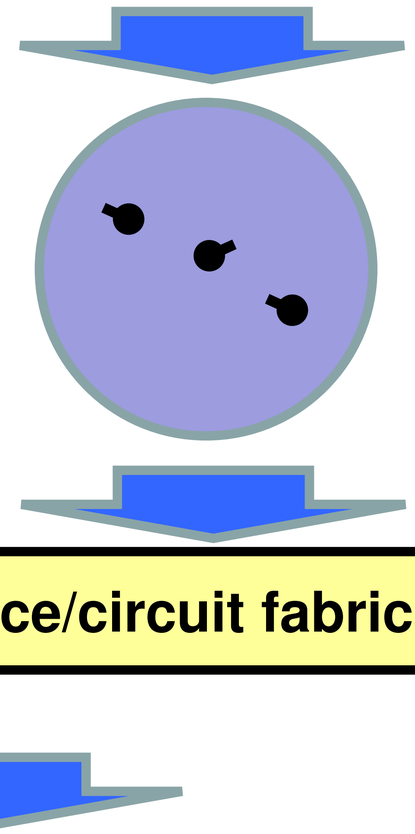
ITES

Passion for Truth

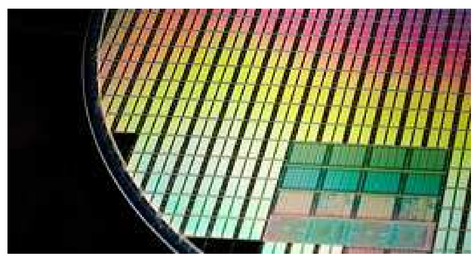
Comparison of conventional chip burn-in and E-V-C method

Conventional Burn-In Screening

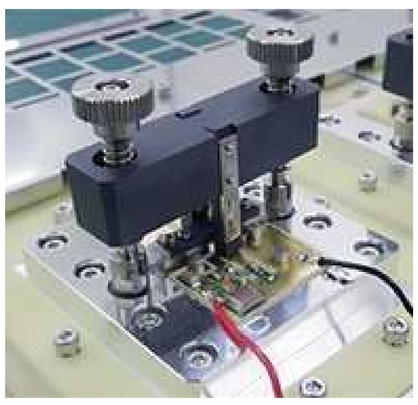
Epi wafer acceptance inspection



Device/circuit fabrication



Packaging





https://www.tmele.jp/case/256/

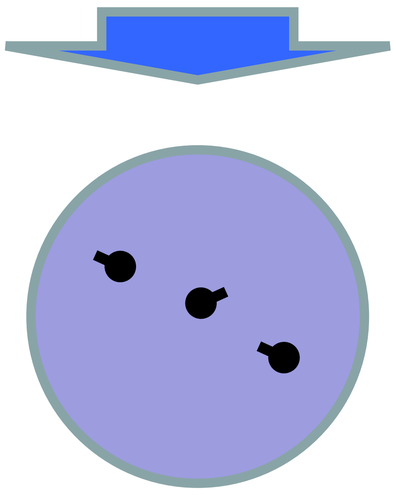
chip burn-in **product burn-in**

Electrical Testing (On resistance, etc.)

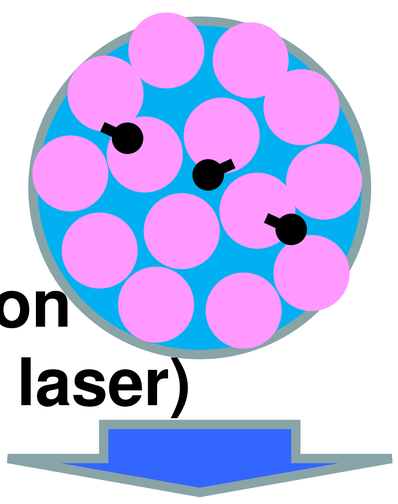
Shipping

Proposed E-V-C Screening

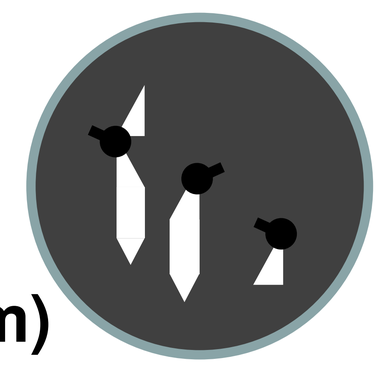
Epi wafer acceptance inspection



Expand
UV irradiation
(355nm, UV laser)



Visualize
UVPL
(BPF420nm)



Defect map obtained

Contract
Heating

Device/circuit fabrication

Shipping

Contact: SiC@ites.co.jp